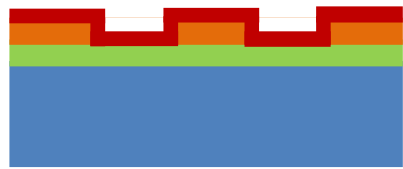
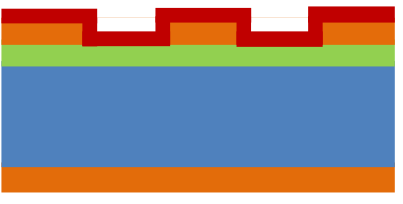

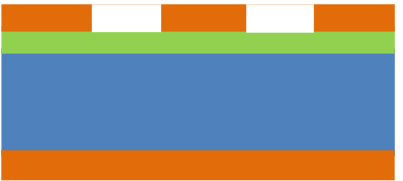




MOSCapacitor Fabrication



Date	Bay	Process	Device cross section
	Wet etch	RCA Cleaning	
	Diffusion	Silicon oxide growth	
	Inline characterisation	Inspection: thickness measurement	
	Thin Films	Front Metal evaporation	
	Lithography	Patterning	
	Wet etch	Metal etch	
	Lithography	Spin coat resist(wafer front side)	

	Wet etch	Back oxide etch	
	Thin Films	Back metal evaporation	
	Wet etch	Resist strip	
	Diffusion	Annealing	



Silicon



Photoresist

Silicon
oxide

Metal